An RGBW Color VGA Rolling and Global Shutter Dynamic and Active-Pixel Vision Sensor

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Abstract—This paper reports the design of a color dynamic and active-pixel vision sensor (C-DAVIS) for robotic vision applications. The C-DAVIS combines monochrome event-generating dynamic vision sensor pixels and 5-transistor active pixels sensor (APS) pixels patterned with an RGBW color filter array. The C-DAVIS concurrently outputs rolling or global shutter RGBW coded VGA resolution frames and asynchronous monochrome QVGA resolution temporal contrast events. Hence the C-DAVIS is able to capture spatial details with color and track movements with high temporal resolution while keeping the data output sparse and fast. The C-DAVIS chip is fabricated in TowerJazz 0.18um CMOS image sensor technology. An RGBW 2x2-pixel unit measures 20x20um². The chip die measures 8x6.2mm².

I. INTRODUCTION

Dynamic vision sensors (**DVS**) [1]-[2] asynchronously output address-events in response to scene reflectance changes. The DVS has sub-millisecond temporal resolution and latency, and a dynamic range of 120dB, but is unable to provide sufficient information for scene reconstruction and recognition. The asynchronous timebased image sensor (ATIS) [3] addressed this problem by adding an event-triggered pulse width modulated (PWM) intensity readout mechanism to each DVS pixel, but resulted in doubled pixel size and motion artefacts. The recent dynamic and active-pixel vision sensor (DAVIS) [4] integrates the active pixel sensor (APS) circuitry with the DVS by adding only 4 more transistors to the DVS pixel. The DAVIS simultaneously outputs synchronous frames and low-latency asynchronous temporal-contrast events.

The above mentioned developments were built with monochrome pixels. However, color can be crucial in machine vision tasks such as RoboCup small size league soccer, quality inspection and traffic signal detection. An event-based color dynamic vision sensor (cDVS) was explored in [5], but was limited by poor color separation capabilities of native buried double junctions and large circuit area required to process the mixed color signals. The native triple junction asynchronous tri-color vision sensor of [6] also suffers from poor color separation, redundant intensity-based event-frequency encoding, and large pixels.

This paper proposes a color dynamic and active-pixel vision sensor (C-DAVIS) by combining slightly modified DAVIS pixels with state-of-the-art 5-transistor (5T) APS pixels [8] and an RGBW color filter array [7]. The C-DAVIS concurrently outputs synchronous VGA RGBW-coded frames and asynchronous QVGA monochrome temporal contrast events. The frame readout aims to support mainly reconstruction and recognition, hence

prioritizes image quality including spatial resolution and color sensitivity; whereas the event readout aims to support mainly motion analysis, hence remains monochromatic (because natural movement almost never produces equiluminant color changes), and prioritizes low latency, high temporal resolution and sparse data.

II. THE SENSOR DESIGN

The design of the C-DAVIS takes into consideration of the following: the 5T APS pixel is much smaller than the DAVIS pixel; the W filter allows approximately 3 times as much photocurrent generated in a W photodiode as in an R, G, or B photodiode; the DAVIS pixel benefits from a larger photocurrent which improves the signal to noise ratio in both its event readout and frame readout. Hence, this heterogeneous pixel array is arranged as depicted in Figure 1. Under the center of each R, G or B filter lies a pinned photodiode (PPD). Under the center of each W filter lies a buried (un-pinned) photodiode (BPD) that allows a contact to the buried layer. Each PPD is connected to a 5T APS pixel circuit (Figure 2). Each BPD is connected to a DAVIS pixel circuit (Figure 3). The DAVIS circuits fill the space between the APS pixels. 3 APS pixels and 1 DAVIS pixel make one RGBW unit. This 4-pixel RGBW unit measures 20um x 20um, slightly larger than one pixel in [4] (18.5um x 18.5um). The fill factor of the RGBW unit (14%) is less than [4] (22%), but is compensated by micro-lenses.

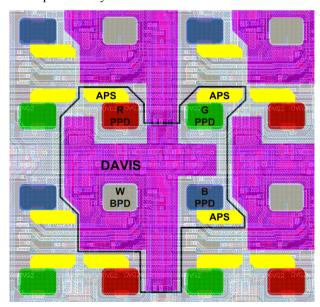


Figure 1 Pixel array arrangement. Yellow=APS area. Purple=DAVIS area. One RGBW unit is circled in black.

A. The APS and DAVIS pixels

The schematic of the 5T APS pixel with PPD (by Towerjazz) is shown in Figure 2. The PPD allows complete

charge transfer from the PPD to the floating diffusion FD. MN1 is the overflow gate (OVG_2) which sets the overflow level of the PPD and resets the PPD. MN2 is the transfer gate (TX_2) . MN3 is the reset switch (RST) that resets FD. MN4 is the source follower readout input transistor. MN5 is the row select switch (SEL) for the analog output (AO) readout. The pixel function is explained in [8].

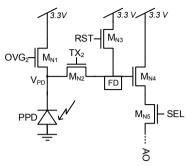


Figure 2 The 5T APS circuit.

A simplified diagram of a DAVIS pixel circuit is shown in Figure 3. Similar to [4], the DAVIS circuit consists of two parts, the "APS part" and the "DVS part". The "APS part" is modified from [4] by adding the reset switch M_{N3} and the integration capacitor C_P. The reason for this change is to make the DAVIS pixel controllable in the same way as the 5T APS pixel for the frame readout (see section III). The "DVS part" is borrowed from [4] but with a revamped layout to fit the space between the APS pixels. The "DVS part" communicates an ON event through the address event representation (AER) logic block when there is an increase in brightness (log intensity) and an OFF event when there is a decrease in brightness.

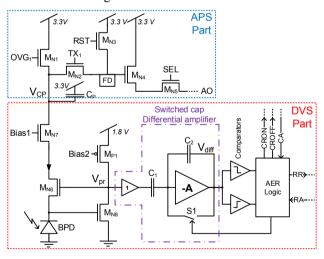


Figure 3 The DAVIS pixel circuit.

The frame readout comes from the APS pixels and the "APS part" of the DAVIS pixels, and employs a unified timing control for both the APS and the DAVIS pixels to reduce complexity. The frame readout can switch between rolling and global shutter modes. The event readout is the same as [4], communicating ON/OFF events through the address event representation (AER) logic when there is an increase/decrease in log intensity.

B. The frame readout logic

The frame readout logic employs unified timing control for both the APS and the DAVIS pixels to reduce logic and wiring complexity. RST and SEL signals are shared among the APS and the DAVIS. OVG1 and OVG2 share the same timing but have separate programmable logic high and low levels. The same goes for TX1 and TX2. The readout has both rolling and global shutter modes.

The rolling shutter control scheme is explained with the timing diagram in Figure 4.

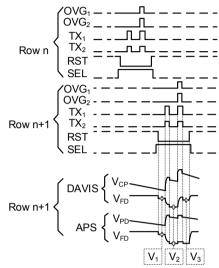


Figure 4 Rolling shutter timing diagram.

In a DAVIS pixel, the photocurrent integrates on C_P . V_{CP} saturates when it reaches one threshold below OVG_1 . In an APS pixel, the photocurrent integrates on the PPD. The PPD's saturation level is determined by OVG_2 . When a row is selected, RST is turned off and the reset level V_1 is sampled via AO. Then TX_1 and TX_2 are turned on to perform charge sharing between C_P and FD in the DAVIS and charge transfer from PPD to FD in the APS. When TX_1 and TX_2 are turned off, the exposure of this row ends. The signal level V_2 is then sampled via AO. In the APS, charge accumulated on PPD is completely transferred to FD, so the accumulated charge Q_{APS} can be computed via correlated double sampling (CDS) off-chip as:

$$Q_{APS} = C_{FD} \cdot (V_1 - V_2)$$

In the DAVIS, charge accumulated on C_P is not completely transferred to FD. To compute the amount of accumulated charge Q_{DAVIS} , a third sample is needed. OVG₁ and OVG₂ are turned on to reset C_P and PPD. Meanwhile TX_1 and TX_2 are turned on. Immediately after OVG₁ and OVG₂ are turned off, TX_1 and TX_2 are also switched off. A third sample V_3 is obtained though AO. V_3 is irrelevant to the APS. But in the DAVIS, V3 is the reset level of C_P . And Q_{DAVIS} can be computed off-chip as:

$$Q_{DAVIS} = C_{FD} \cdot (V_1 - V_2) + C_P \cdot (V_3 - V_2)$$

Triple sampling is performed in the DAVIS to remove the fixed pattern noise (FPN) caused by offsets in the reset levels of both C_P and FD. However, the three samples are uncorrelated and the kTC noise introduced by TX_1 and OVG_1 cannot be removed. The three samples are acquired with minimum temporal separation in order to minimize 1/f noise introduced by M_{N4} [9]. 3 samples per row-select may increase the individual row time and thus motion

distortions. However, for the C-DAVIS, rolling shutter readout is meant for capturing static scenes. When the frame readout is distorted due to motion, the asynchronous event readout could allow off chip corrections.

The global shutter control scheme minimizes motion artefacts, but with the tradeoff of higher noise. The timing diagram is illustrated in Figure 5.

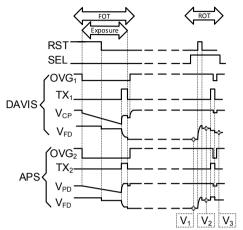


Figure 5 Global shutter timing diagram.

During the global frame overhead time (FOT), OVG_1 and OVG_2 are lowered to initiate the exposure. Exposure is ended by simultaneously turning TX_1 and TX_2 off. At the end of the exposure, each pixel has stored a signal level in its FD for the row by row readout.

During a row overhead time (ROT), one row is selected by turning SEL on. The signal level V_1 is sampled via AO, followed by a RST pulse, then a sample of the reset level V_2 via AO. In the APS, the accumulated charge Q_{APS} can be computed off-chip as below:

$$Q_{APS} = C_{FD} \cdot (V_2 - V_1)$$

In the DAVIS, a third sample is needed to compute Q_{DAVIS} . TX_1 and TX_2 are turned on and OVG_1 and OVG_2 are turned off to allow FD to sample the reset level of C_P . After TX_1 and TX_2 are turned off, the third sample V_3 is obtained. And Q_{DAVIS} can be computed off-chip as:

$$Q_{DAVIS} = C_{FD} \cdot (V_2 - V_1) + C_P \cdot (V_3 - V_1)$$

The global shutter control scheme performs differential double sampling in the APS and triple sampling in the DAVIS which removes FPN caused by offsets in the reset levels of FD and C_P. But kTC noise introduced by RST and TX₁ will remain. Because global shutter requires high shutter efficiency, both the APS and the DAVIS pixel have metal shielding and dedicated implants to reduce FD leakage. Moreover, the control logic is designed to have the flexibility to implement a different double sampling global shutter control scheme as seen in [4] to cancel out the effect of FD leakage in reset and signal samples, at the cost of increased 1/f noise.

C. The integration

To output uniform frames from this heterogeneous pixel array, the frame readout of the APS and the DAVIS pixels should have matching parameters. The APS pixel's conversion gain is determined solely by the capacitance of FD, while the DAVIS pixel's conversion gain is determined by both the capacitance of FD and CP.

Considering that the BPD receives approximately 3 times as many photons as the PPD receives under natural illumination, due to the optical efficiency difference between R, G, B and W filters, the combined capacitance of FD and CP is designed to be 3 times of the capacitance of FD. Also, the integration capacity of the DAVIS is designed to be 3 times of the APS. This way, although a DAVIS BPD receives approximately 3 times as many photons as an APS PPD, two types of pixels saturate at about the same time during exposure and have similar range of output swing.

Because the heterogeneous pixel array concurrently produces both frame and event outputs, significant design efforts were spent on minimizing crosstalk between the frame readout and the event readout. As a lesson learned from [4], the largest disturbance comes from the frame readout control signals, especially in global shutter mode. To reduce their impact on the event readout, careful signal separation and shielding were done in pixel layout. All frame readout control signals are driven by buffers with programmable slew rate. All event readout biases are driven by programmable analog buffers distributed in every column.

The C-DAVIS chip contains a programmable bias generator, 10-bit column-parallel ADC and test features. A picture of the chip layout is shown in Figure 6.

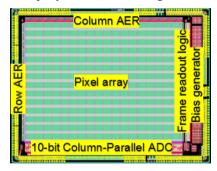


Figure 6 C-DAVIS chip layout.

III. EXPERIMENTAL RESULTS

To support the C-DAVIS chip, a mother-daughter PCB setup was developed, which contains, among many other features, USB3.0 interface and an FPGA. The open-source software project jAER [10] is used to control, display, record, and process the output of the sensor.

Figure 7 shows the raw rolling shutter frame output without interpolation. In the scene there is a spinning white disk with a straight black bar on the left and a standard color checker on the right. The scene is illuminated with normal office lighting measured 240lux at the surface of the color checker. It is noticeable that in the W (bottomleft) quadrant, the darker region has grainy black dots (as shown in the zoomed-in red square). The same effect can be observed in the W pixel global shutter output too. The speculated reason is that in the W (DAVIS) pixel, the photocurrent integrates on C_P during exposure, and when there is less light, CP remains at a relatively high voltage level, making TX₁ difficult to be fully on. The accumulated charge cannot be transferred to the FD as fast as in the APS pixel. The variation in the TX₁ transfer speed results in the grainy black dots effect. This hypothesis has been confirmed by observing that the effect is alleviated by

increasing the charge transfer time. However, increasing charge transfer time is not able to eliminate this effect. In the follow-up experiments, a different global shutter readout logic [4] will be tested, which is a possible solution to achieve good performance in both the DAVIS and the APS frame output.

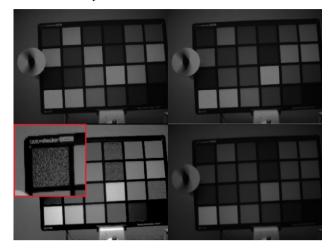


Figure 7 Rolling shutter frame output without interpolation. The four quadrants corresponds to (clockwise from top-left): the R (APS) pixels, G (APS) pixels, B (APS) pixels and W (DAVIS) pixels.

Figure 8 shows the space-time view of the dual-output data of the same scene with the same illumination (240lux). The full color VGA frame is achieved by simple linear interpolation only (excluding W pixels). The 306ms time slice contains 1 million events, which clearly trace the rotation of the black bar with high temporal resolution.

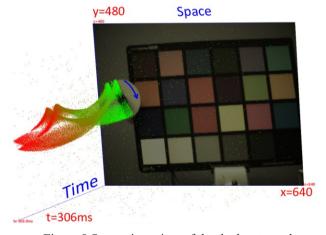


Figure 8 Space-time view of the dual-output, the interpolated full color frame and the events from the rotating black bar on the white disk. Green events are older, red events are newer.

Table *I* summarizes the specifications of the chip in comparison to [4]. The significant increase in power consumption compared to [4] is due to the increase in pixel numbers, more complex APS control logic circuitry and the on-chip column parallel ADC. The event readout alone only consumes about 15-32mW depending on the amount of movement in the scene. Other key characteristics such as the dynamic range, FPN, dark signal of the frame output

and the latency, bandwidth, sensitivity of the event output will be measured in the follow-up experiments.

Table 1 C-DAVIS vs. DAVIS Design Specifications

	This work	DAVIS [4]
Fabrication	6M1P 0.18um CIS	6M1P 0.18um CIS
process	process with MIM	process with MIM
Supply voltage	3.3V analog	3.3V analog
	1.8V/4V digital	1.8V digital
Resolution	640 x 480 Frame	240 x 180
	320 x 240 Event	frame and event
Pixel size	2x2 pixels: 20x20um ²	1 pixel: 18.5x18.5um ²
Pixel complexity	2x2 pixels: 56 fets	1 pixel: 44 fets
	3 MIMcaps	2 MIMcaps
	4 photodiodes	1 photodiodes
Fill factor	14% (not considering	22%
	micro-lenses)	22/0
Die size	8x6.2mm ²	5x5mm ²
Power	106-120mW	5-14mW
consumption		

IV. DISCUSSION

By combining the DAVIS and the APS, the C-DAVIS is able to utilize the focal plane area and fit under a standard RGBW color filter array. Although the proposed triple sampling frame readout increases the amount of data per frame, for robotic vision applications the frame rate is designed to be data-driven with the help of the event readout. The frame readout logic is also flexible and allows double sampling as [4]. The initial testing has found the chip functional as designed. Further experiment results will be reported later.

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